

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Switch-mode Soft Ultrafast Recovery Reverse Polarity Power Rectifier

State-of-the-art geometry features epitaxial construction with glass passivation. Ideally suited for low voltage, high frequency switching power supplies, free wheeling diode and polarity protection diodes.

Features

- Soft Ultrafast Recovery
- Matched Dual Die Construction May Be Paralleled for High Current Output
- Short Heat Sink Tab Manufactured Not Sheared
- Epoxy Meets UL 94 V-0 @ 0.125 in.
- NRVSRD and SSRD8 Prefixes for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant*

Mechanical Characteristics

- Case: Epoxy, Molded
- Weight: 0.4 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- ESD Ratings:
 - ◆ Machine Model = C
 - ◆ Human Body Model = 2



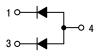
ON Semiconductor®

www.onsemi.com

SOFT ULTRAFAST REVERSE POLARITY RECTIFIER 6.0 AMPERES, 200 VOLTS



DPAK CASE 369C



MARKING DIAGRAM



A = Assembly Location

Y = Year WW = Work Week

G = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping [†]
MSRD620CTRG	DPAK (Pb-Free)	75 Units/Rail
SSRD8620CTRG	DPAK (Pb-Free)	75 Units/Rail
MSRD620CTT4RG	DPAK (Pb-Free)	2,500 / Tape & Reel
NRVSRD620VCTT4RG	DPAK (Pb-Free)	2,500 / Tape & Reel
SSRD8620CTT4RG	DPAK (Pb-Free)	2,500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	200	V
Average Rectified Forward Current (At Rated V _R , T _C = 162°C) Per Leg Per Package	I _O	3.0 6.0	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions, Halfwave, Single Phase, 60 Hz) Per Package	I _{FSM}	45	А
Storage/Operating Case Temperature	T _{stg} , T _c	-65 to +175	°C
Operating Junction Temperature	TJ	-65 to +175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal Resistance – Junction–to–Case (Note 1) Per Leg	$R_{ heta JC}$	5.0	°C/W
Thermal Resistance – Junction–to–Ambient (Note 1) Per Leg	$R_{ heta JA}$	60	°C/W
Thermal Resistance – Junction–to–Ambient (Note 2) Per Leg	$R_{ hetaJA}$	166	°C/W

Mounted with 700 mm² copper pad size (approximately 1 in²) 1 oz FR4 board.
 Mounted with pad size approximately 46 mm² copper, 1 oz FR4 board.

ELECTRICAL CHARACTERISTICS

Rating	Symbol	Va	lue	Unit
Maximum Instantaneous Forward Voltage (Note 3)	V _F	T _J = 25°C	T _J = 125°C	V
Per Leg (I _F = 3.0 A) (I _F = 6.0 A)		1.15 1.30	0.95 1.15	
Maximum Instantaneous Reverse Current (Note 3) Per Leg	I _R	T _J = 25°C	T _J = 125°C	μΑ
(V _R = 200 V)		1.0	200	
Maximum Reverse Recovery Time (Note 4) Per Lea	t _{rr}			ns
$(V_R = 30 \text{ V}, I_F = 1.0 \text{ A}, \text{ di/dt} = 50 \text{ A/}\mu\text{s})$		7	5	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 3. Pulse Test: Pulse Width \leq 380 µs, Duty Cycle \leq 2%.

^{4.} t_{rr} measured projecting from 25% of I_{BM} to ground.

TYPICAL CHARACTERISTICS

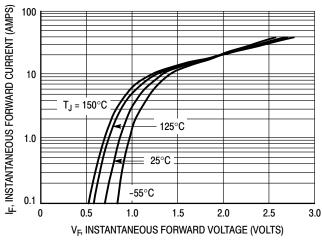


Figure 1. Typical Forward Voltage, Per Leg

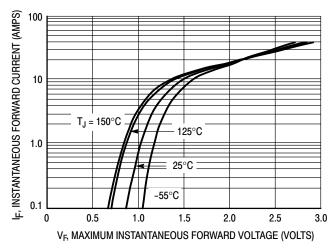
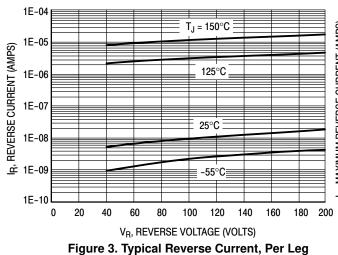


Figure 2. Maximum Forward Voltage, Per Leg



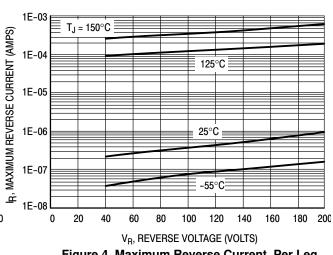


Figure 4. Maximum Reverse Current, Per Leg

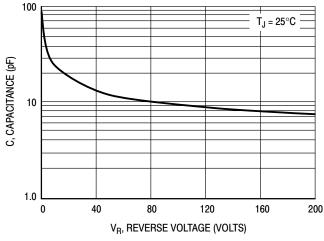


Figure 5. Typical Capacitance

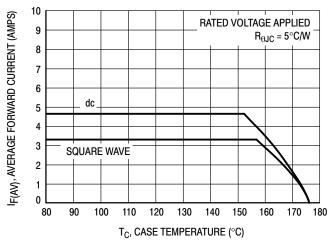


Figure 6. Typical Current Derating, Case (Per Leg)

TYPICAL CHARACTERISTICS

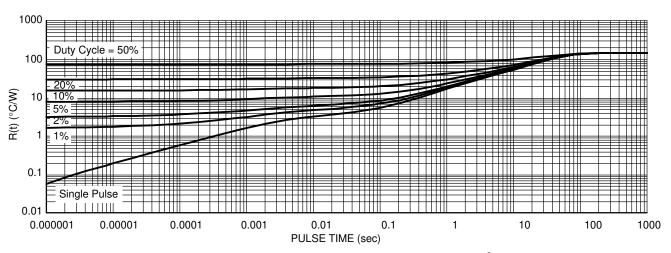


Figure 7. Thermal Response, Junction-to-Ambient (46 mm² pad)

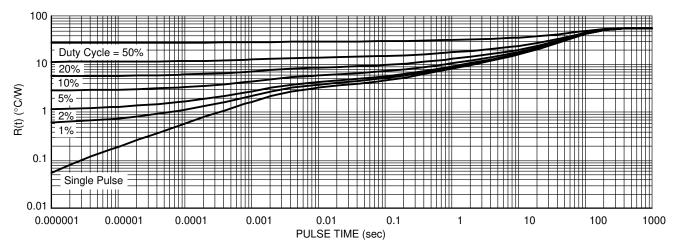
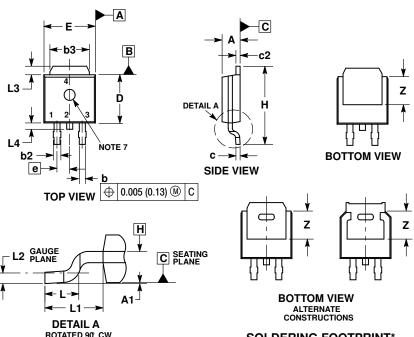


Figure 8. Thermal Response, Junction-to-Ambient (1 in² pad)

PACKAGE DIMENSIONS

DPAK (SINGLE GAUGE)

CASE 369C ISSUE F



- OTLO.

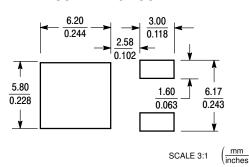
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

 2. CONTROLLING DIMENSION: INCHES.
- 3. THERMAL PAD CONTOUR OPTIONAL WITHIN DI-MENSIONS b3, L3 and Z.
 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD
- FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
 5. DIMENSIONS D AND E ARE DETERMINED AT THE
- OUTERMOST EXTREMES OF THE PLASTIC BODY.

 6. DATUMS A AND B ARE DETERMINED AT DATUM
- 7. OPTIONAL MOLD FEATURE.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.028	0.045	0.72	1.14
b3	0.180	0.215	4.57	5.46
С	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
Е	0.250	0.265	6.35	6.73
е	0.090	BSC	2.29	BSC
Н	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.114	REF	2.90 REF	
L2	0.020 BSC		0.51 BSC	
L3	0.035	0.050	0.89	1.27
L4		0.040		1.01
Z	0.155		3.93	

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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